

ABSTRACT

SOLDER BALL DISPOSING APPARATUS, SOLDER BALL REFLOW APPARATUS, AND SOLDER BALL BONDING APPARATUS

An apparatus joins bonding pads of a slider and lead pads of lead wires in a head gimbals assembly to improve efficiency, downsizing, and maintenance of solder-ball disposing devices, and solder-ball reflow devices for reflowing solder balls. The solder-ball disposing apparatus discharges solder balls from solder-ball discharging holes of a solder-ball feeder unit which are evacuated by a suction pad. An environmental space and an inert-gas supply portion for forming inactive atmosphere are formed on a table to eliminate an inert-gas supply unit from an optical unit, so that converged laser beams are directly radiated onto the solder balls.

20074718-021302